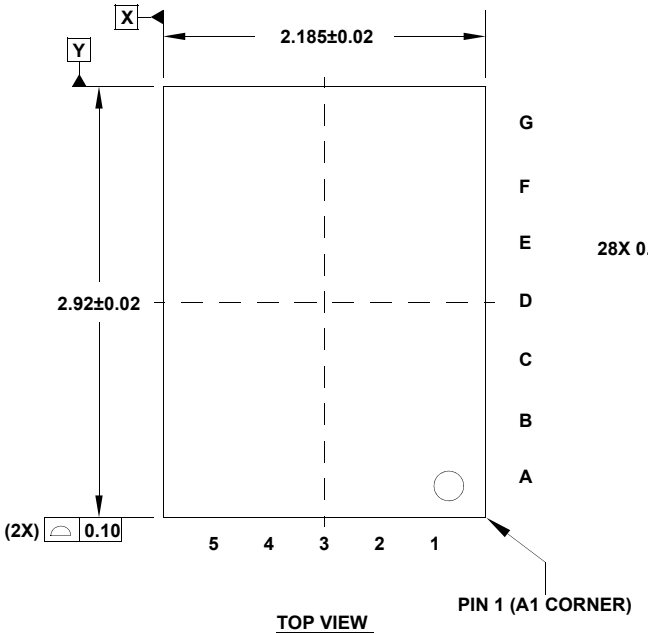
Package Outline Drawing

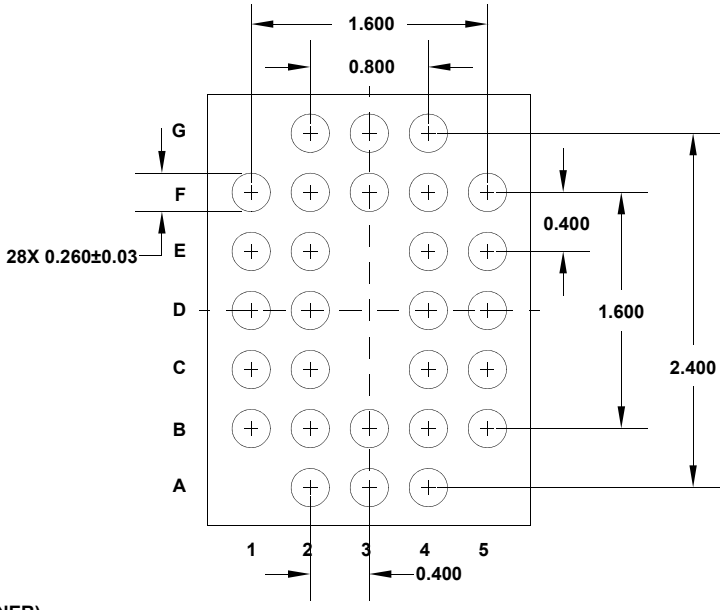
W5x7.28

28 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)

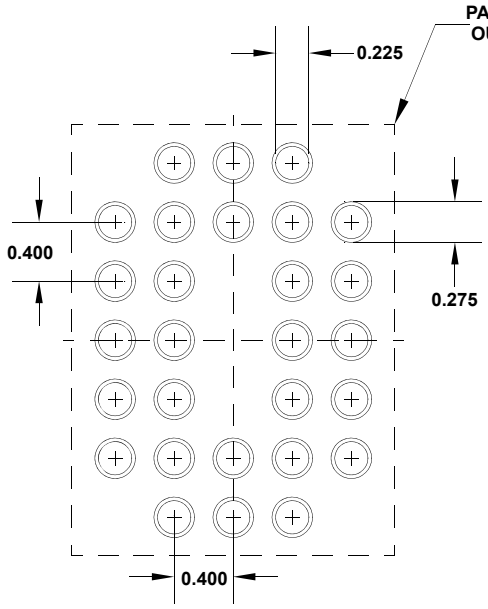
Rev 0, 7/12



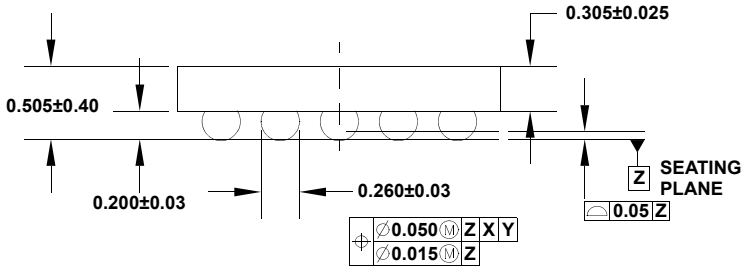
TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. Dimensions and tolerance per ASME Y 14.5M - 1994.
2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.